

Full Material Declaration for attached parts list

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Declarations authorised by:

Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 January 2014 [Approved on 06 February 2026, 13:22 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.48%	Silicon	7440-21-3	100%
Encapsulation	EP (Epoxy resin)	76.02%	Carbon black	1333-86-4	1%
			Zinc borate hydrate	12513-27-8	5%
			Phenol, polymer with formaldehyde	9003-35-4	15%
			Oxirane, (chloromethyl)-, homopolymer	24969-06-0	19%
			Silicon Dioxide	7631-86-9	60%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.05%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	0.48%	Tin	7440-31-5	100%
Leadframe	Steel and iron materials	22.97%	SILVER, ELEMENTAL	7440-22-4	4.5%
			Elemental nickel REACH Article 67 Exemption	7440-02-0	40.34%
			Iron	7439-89-6	55.16%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOD-123 (EB) Pb&H-free	Diode SMD	0.01052	g

